

Data Sheet January 2004 FN6071

# 3.3V, Low Power, 30Mbps, RS-485/RS-422 Transceiver

The Intersil ISL43485 is a high speed BiCMOS 3.3V powered, single transceiver that meets both the RS-485 and RS-422 standards for balanced communication. Unlike some competitive devices, this Intersil transceiver is specified for 10% tolerance supplies (3V to 3.6V).

Data rates up to 30Mbps are achievable by using this transceiver, which features higher slew rates.

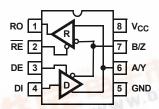
Logic inputs (e.g., DI and DE) accept signals in excess of 5.5V, making them compatible with 5V logic families.

Receiver (Rx) inputs feature a "fail-safe if open" design, which ensures a logic high output if Rx inputs are floating, and the ISL43485 presents a "single unit load" to the RS-485 bus, which allows up to 32 transceivers on the network.

Driver (Tx) outputs are short circuit protected, even for voltages exceeding the power supply voltage. Additionally, on-chip thermal shutdown circuitry disables the Tx outputs to prevent damage if power dissipation becomes excessive.

#### **Pinout**

ISL43485 (SOIC) TOP VIEW



#### Features

- High Data Rate..... up to 30Mbps
- Operates from a Single +3.3V Supply (10% Tolerance)
- Interoperable with 5V Logic
- Single Unit Load Allows up to 32 Devices on the Bus
- -7V to +12V Common Mode Input Voltage Range
- · Three State Rx and Tx Outputs
- · 10ns Propagation Delay, 1ns Skew
- Half Duplex Pinout
- Current Limiting and Thermal Shutdown for driver Overload Protection

## **Applications**

- · SCSI "Fast 20" Drivers and Receivers
- · Factory Automation
- · Data Loggers
- · Security Networks
- Building Environmental Control Systems
- Industrial/Process Control Networks
- Level Translators

## **Ordering Information**

PART NO. (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
ISL43485IB (43485IB)	-40 to 85	8 Ld SOIC	M8.15
ISL43485IB-T (43485IB)	-40 to 85	8 Ld SOIC Tape and Reel	M8.15



## Truth Tables

TRANSMITTING							
	INPUTS	OUTPUTS					
RE	DE	DI	Z	Y			
X	1	1	0	1			
Х	1	0	1	0			
0	0	Х	High-Z	High-Z			
1	0	Х	High-Z *	High-Z *			

NOTE: \*Shutdown Mode

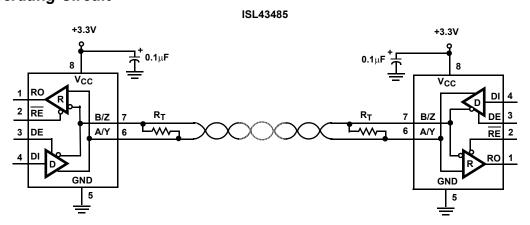
RECEIVING						
	OUTPUT					
RE	DE	A-B	RO			
0	0	≥ +0.2V	1			
0	0	≤ -0.2V	0			
0	0	Inputs Open	1			
1	0	Х	High-Z *			
1	1	Х	High-Z			

NOTE: \*Shutdown Mode

# Pin Descriptions

PIN	FUNCTION
RO	Receiver output: If A > B by at least 0.2V, RO is high; If A < B by 0.2V or more, RO is low; RO = High if A and B are unconnected (floating).
RE	Receiver output enable. RO is enabled when $\overline{RE}$ is low; RO is high impedance when $\overline{RE}$ is high.
DE	Driver output enable. The driver outputs, Y and Z, are enabled by bringing DE high. They are high impedance when DE is low.
DI	Driver input. A low on DI forces output Y low and output Z high. Similarly, a high on DI forces output Y high and output Z low.
GND	Ground connection.
A/Y	Noninverting receiver input and noninverting driver output. Pin is an input if DE = 0; pin is an output if DE = 1.
B/Z	Inverting receiver input and inverting driver output. Pin is an input if DE = 0; pin is an output if DE = 1.
V <sub>CC</sub>	System power supply input (3V to 3.6V).

# **Typical Operating Circuit**



## ISL43485

## **Absolute Maximum Ratings**

V <sub>CC</sub> to Ground	
Input Voltages	
DI, DE, RE	0.5V to +7V
Input/Output Voltages	
A/Y, B/Z	8V to +12.5V
RO	0.5V to (V <sub>CC</sub> +0.5V)
Short Circuit Duration	,
Y, Z	Continuous

#### **Thermal Information**

Thermal Resistance (Typical, Note 1)	θ <sub>JA</sub> (°C/W)
8 Ld SOIC Package	170
Maximum Junction Temperature (Plastic Package)	
Maximum Storage Temperature Range6	5°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(Lead Tips Only)	

## **Operating Conditions**

Temperature Range ISL43485I....-40°C to 85°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1. θ<sub>JA</sub> is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

## Electrical Specifications Test Conditions: V<sub>CC</sub> = 3V to 3.6V; Unless Otherwise Specified. Typicals are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = 25°C,

PARAMETER	SYMBOL	TEST CONDITION	IS	TEMP (°C)	MIN	TYP	MAX	UNITS
DC CHARACTERISTICS					I	I		11.
Driver Differential V <sub>OUT</sub> (no load)	V <sub>OD1</sub>			Full	-	-	V <sub>CC</sub>	V
Driver Differential V <sub>OUT</sub> (with load)	V <sub>OD2</sub>	$R_L = 100\Omega \text{ (RS-422) (Figure 1A)}$		Full	2	2.7	-	V
		$R_L$ = 54Ω (RS-485) (Figure 1A)		Full	1.5	2.3	V <sub>CC</sub>	V
		$R_L = 60\Omega$ , $-7V \le V_{CM} \le 12V$ (Figu	ure 1B)	Full	1.5	2.6	-	V
Change in Magnitude of Driver Differential V <sub>OUT</sub> for Complementary Output States	ΔV <sub>OD</sub>	R <sub>L</sub> = 54Ω or 100Ω (Figure 1A)		Full	-	0.01	0.2	V
Driver Common-Mode V <sub>OUT</sub>	V <sub>OC</sub>	$R_L$ = 54Ω or 100Ω (Figure 1A)	$R_L = 54\Omega$ or $100\Omega$ (Figure 1A)		-	1.8	3	V
Change in Magnitude of Driver Common-Mode V <sub>OUT</sub> for Complementary Output States	ΔV <sub>OC</sub>	R <sub>L</sub> = 54 $\Omega$ or 100 $\Omega$ (Figure 1A)		Full	-	0.01	0.2	V
Logic Input High Voltage	V <sub>IH</sub>	DE, DI, RE		Full	2	-	-	V
Logic Input Low Voltage	V <sub>IL</sub>	DE, DI, RE		Full	-	-	0.8	V
Logic Input Current	I <sub>IN1</sub>	DE, DI		Full	-2	-	2	μА
		RE		Full	-25	-	25	μА
Input Current (A/Y, B/Z)	I <sub>IN2</sub>	DE = 0V, V <sub>CC</sub> = 0V or 3.6V	V <sub>IN</sub> = 12V	Full	-	0.6	1	mA
			V <sub>IN</sub> = -7V	Full	-	-0.3	-0.8	mA
Receiver Differential Threshold Voltage	$V_{TH}$	$-7V \le V_{CM} \le 12V$	$-7V \le V_{CM} \le 12V$		-0.2	-	0.2	V
Receiver Input Hysteresis	$\Delta V_{TH}$	V <sub>CM</sub> = 0V		25	-	50	-	mV
Receiver Output High Voltage	V <sub>OH</sub>	I <sub>O</sub> = -4mA, V <sub>ID</sub> = 200mV		Full	V <sub>CC</sub> - 0.4	-	-	V
Receiver Output Low Voltage	V <sub>OL</sub>	I <sub>O</sub> = -4mA, V <sub>ID</sub> = 200mV		Full	-	-	0.4	V

-----

**Electrical Specifications** Test Conditions:  $V_{CC}$  = 3V to 3.6V; Unless Otherwise Specified. Typicals are at  $V_{CC}$  = 3.3V,  $T_A$  = 25°C, Note 2 **(Continued)** 

	NOTE 2 (COIL							
PARAMETER	SYMBOL	TEST CONDITIONS		TEMP (°C)	MIN	TYP	MAX	UNITS
Three-State (high impedance) Receiver Output Current	I <sub>OZR</sub>	$0.4V \leq V_O \leq 2.4V$	$0.4V \le V_O \le 2.4V$		-1	-	1	μА
Receiver Input Resistance	R <sub>IN</sub>	$-7V \le V_{CM} \le 12V$	7V ≤ V <sub>CM</sub> ≤ 12V		12	19	-	kΩ
No-Load Supply Current (Note 3)	Icc	$DI = 0V \text{ or } V_{CC}$ $\frac{DE}{RE} = V_{CC},$ $RC$ or $V_{CC}$		Full	-	0.75	1.2	mA
			<u>DE</u> = 0V, RE = 0V	Full	-	0.65	1	mA
Shutdown Supply Current	I <sub>SHDN</sub>	DE = 0V, $\overline{RE}$ = V <sub>CC</sub> , DI = 0V or V <sub>CC</sub>		Full	-	15	100	nA
Driver Short-Circuit Current, V <sub>O</sub> = High or Low	l <sub>OSD1</sub>	DE = $V_{CC}$ , $-7V \le V_Y$ or $V_Z \le 12V$ (Not	DE = $V_{CC}$ , -7V $\leq$ V <sub>Y</sub> or V <sub>Z</sub> $\leq$ 12V (Note 4)		-	-	250	mA
Receiver Short-Circuit Current	losr	$0V \le V_O \le V_{CC}$		Full	8	-	60	mA
DRIVER SWITCHING CHARACTE	RISTICS							
Maximum Data Rate	f <sub>MAX</sub>	(Figure 2A)	Figure 2A)			50	-	Mbps
Driver Differential Output Delay	t <sub>DD</sub>	$R_{DIFF}$ = 60 $\Omega$ , $C_L$ = 15pF (Figure 2A)		Full	3	10	25	ns
Driver Differential Rise or Fall Time	t <sub>R</sub> , t <sub>F</sub>	$R_{DIFF} = 60\Omega$ , $C_L = 15pF$ (Figure 2A)			3	6	12	ns
Driver Input to Output Delay	t <sub>PLH</sub> , t <sub>PHL</sub>	$R_L = 27\Omega$ , $C_L = 15pF$ (Figure 2C)			6	10	22	ns
Driver Output Skew	t <sub>SKEW</sub>	$R_L = 27\Omega$ , $C_L = 15pF$ (Figure 2C)			-	1	5	ns
Driver Enable to Output High	t <sub>ZH</sub>	$R_L = 110\Omega$ , $C_L = 50$ pF, SW = GND (Figure 3), (Note 5)			-	45	90	ns
Driver Enable to Output Low	t <sub>ZL</sub>	$R_L = 110\Omega$ , $C_L = 50$ pF, SW = $V_{CC}$ (Figure 3), (Note 5)		Full	-	45	90	ns
Driver Disable from Output High	t <sub>HZ</sub>	$R_L$ = 110 $\Omega$ , $C_L$ = 50pF, SW = GND (Fi	gure 3)	Full	-	60	90	ns
Driver Disable from Output Low	t <sub>LZ</sub>	$R_L$ = 110 $\Omega$ , $C_L$ = 50pF, SW = $V_{CC}$ (Fig.	gure 3)	Full	-	70	100	ns
Driver Enable from Shutdown to Output High	t <sub>ZH(SHDN)</sub>	$R_L = 110\Omega$ , $C_L = 50pF$ , SW = GND (Final (Notes 7, 8)	gure 3),	Full	-	115	150	ns
Driver Enable from Shutdown to Output Low	t <sub>ZL</sub> (SHDN)	$R_L$ = 110 $\Omega$ , $C_L$ = 50pF, SW = $V_{CC}$ (Fig. (Notes 7, 8)	gure 3),	Full	-	115	150	ns
RECEIVER SWITCHING CHARAC	TERISTICS					1	I	
Maximum Data Rate	f <sub>MAX</sub>	$V_{ID} \ge 1.5V$ with $t_f/t_f$ = 10ns, RO $t_H$ & $t_L$ (Figure 4)	_ ≥ 60% t <sub>UI</sub>	Full	27	35	-	Mbps
Receiver Input to Output Delay	t <sub>PLH</sub> , t <sub>PHL</sub>	(Figure 4)			25	45	80	ns
Receiver Skew   t <sub>PLH</sub> - t <sub>PHL</sub>	t <sub>SKD</sub>	(Figure 4)		Full	-	2	12	ns
Receiver Enable to Output High	t <sub>ZH</sub>	$R_L = 1k\Omega$ , $C_L = 15pF$ , $SW = GND$ (Figure 5), (Note 6)		Full	-	11	25	ns
Receiver Enable to Output Low	t <sub>ZL</sub>	$R_L = 1k\Omega$ , $C_L = 15pF$ , $SW = V_{CC}$ (Figure 5), (Note 6)		Full	-	11	25	ns
Receiver Disable from Output High	t <sub>HZ</sub>	$R_L = 1k\Omega$ , $C_L = 15pF$ , SW = GND (Figure 5)			-	7	20	ns
Receiver Disable from Output Low	t <sub>LZ</sub>	$R_L = 1k\Omega$ , $C_L = 15pF$ , SW = $V_{CC}$ (Figure 1)	ure 5)	Full	-	7	20	ns

# **Electrical Specifications** Test Conditions: $V_{CC} = 3V$ to 3.6V; Unless Otherwise Specified. Typicals are at $V_{CC} = 3.3V$ , $T_A = 25$ °C, Note 2 (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	TEMP (°C)	MIN	ТҮР	MAX	UNITS
Time to Shutdown	tSHDN	(Note 7)	Full	80	190	300	ns
Receiver Enable from Shutdown to Output High	t <sub>ZH</sub> (SHDN)	$R_L$ = 1k $\Omega$ , $C_L$ = 15pF, SW = GND (Figure 5), (Notes 7, 9)	Full	-	240	400	ns
Receiver Enable from Shutdown to Output Low	t <sub>ZL(SHDN)</sub>	$R_L = 1k\Omega$ , $C_L = 15pF$ , $SW = V_{CC}$ (Figure 5), (Notes 7, 9)	Full	-	240	400	ns

#### NOTES:

- 2. All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.
- 3. Supply current specification is valid for loaded drivers when DE = 0V.
- 4. Applies to peak current. See "Typical Performance Curves" for more information.
- 5. When testing this parameter, keep  $\overline{RE} = 0$  to prevent the device from entering SHDN.
- 6. When testing this parameter, the RE signal high time must be short enough (typically <100ns) to prevent the device from entering SHDN.
- 7. The ISL43485 is put into shutdown by bringing  $\overline{\text{RE}}$  high and DE low. If the inputs are in this state for less than 80ns, the parts are guaranteed not to enter shutdown. If the inputs are in this state for at least 300ns, the parts are guaranteed to have entered shutdown. See "Low-Power Shutdown Mode" section.
- 8. Keep  $\overline{RE}$  = VCC, and set the DE signal low time >300ns to ensure that the device enters SHDN.
- 9. Set the RE signal high time >300ns to ensure that the device enters SHDN.

### Test Circuits and Waveforms

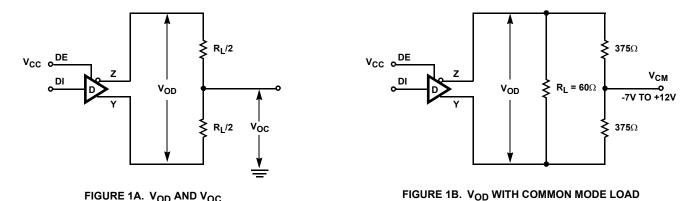


FIGURE 1A.  $V_{OD}$  AND  $V_{OC}$  FIGURE 1B.  $V_{O}$  FIGURE 1. DC DRIVER TEST CIRCUITS

•

## Test Circuits and Waveforms (Continued)

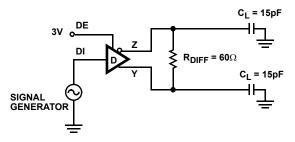


FIGURE 2A. DIFFERENTIAL TEST CIRCUIT

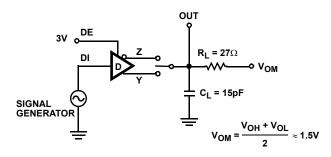


FIGURE 2C. SINGLE ENDED TEST CIRCUIT

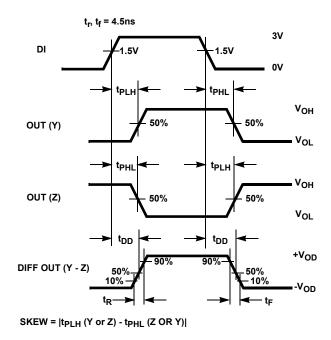
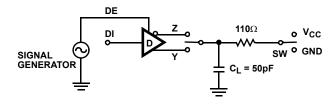


FIGURE 2B. MEASUREMENT POINTS

FIGURE 2. DRIVER DATA RATE, PROPAGATION DELAY AND DIFFERENTIAL TRANSITION TIMES



PARAMETER	OUTPUT	RE	DI	sw
t <sub>HZ</sub>	Y/Z	Х	1/0	GND
$t_{LZ}$	Y/Z	Х	0/1	V <sub>CC</sub>
t <sub>ZH</sub>	Y/Z	0 (Note 5)	1/0	GND
t <sub>ZL</sub>	Y/Z	0 (Note 5)	0/1	V <sub>CC</sub>
t <sub>ZH</sub> (SHDN)	Y/Z	1 (Note 8)	1/0	GND
t <sub>ZL(SHDN)</sub>	Y/Z	1 (Note 8)	0/1	V <sub>CC</sub>

FIGURE 3A. TEST CIRCUIT

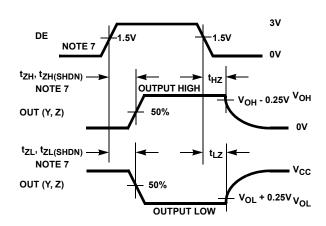


FIGURE 3B. MEASUREMENT POINTS

FIGURE 3. DRIVER ENABLE AND DISABLE TIMES

6 ----

## Test Circuits and Waveforms (Continued)

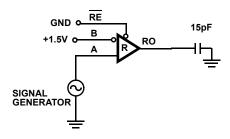


FIGURE 4A. TEST CIRCUIT

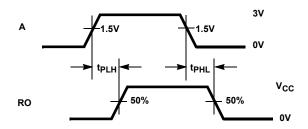
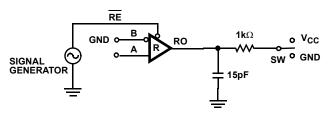


FIGURE 4B. MEASUREMENT POINTS

FIGURE 4. RECEIVER DATA RATE AND PROPAGATION DELAY



PARAMETER	DE	Α	sw
t <sub>HZ</sub>	0	+1.5V	GND
$t_{LZ}$	0	-1.5V	V <sub>CC</sub>
t <sub>ZH</sub> (Note 6)	0	+1.5V	GND
t <sub>ZL</sub> (Note 6)	0	-1.5V	V <sub>CC</sub>
t <sub>ZH(SHDN)</sub> (Note 9)	0	+1.5V	GND
t <sub>ZL(SHDN)</sub> (Note 9)	0	-1.5V	V <sub>CC</sub>

NOTE 7

RE

1.5V

1.5V

0V

tzh, tzh(shdn)

NOTE 7

RO

1.5V

1.5V

0V

1.5V

Voh - 0.25V

Voc

Vol + 0.25V

Vol

FIGURE 5A. TEST CIRCUIT FIGURE 5B. MEASUREMENT POINTS

FIGURE 5. RECEIVER ENABLE AND DISABLE TIMES

## Application Information

RS-485 and RS-422 are differential (balanced) data transmission standards for use in long haul or noisy environments. RS-422 is a subset of RS-485, so RS-485 transceivers are also RS-422 compliant. RS-422 is a point-to-multipoint (multidrop) standard, which allows only one driver and up to 10 (assuming one unit load devices) receivers on each bus. RS-485 is a true multipoint standard, which allows up to 32 one unit load devices (any combination of drivers and receivers) on each bus. To allow for multipoint operation, the RS-485 spec requires that drivers must handle bus contention without sustaining any damage.

Another important advantage of RS-485 is the extended common mode range (CMR), which specifies that the driver outputs and receiver inputs withstand signals that range from +12V to -7V. RS-422 and RS-485 are intended for runs as long as 4000', so the wide CMR is necessary to handle ground potential differences, as well as voltages induced in the cable by external fields.

#### Receiver Features

This device utilizes a differential input receiver for maximum noise immunity and common mode rejection. Input sensitivity is ±200mV, as required by the RS422 and RS-485 specifications.

Receiver input impedance surpasses the RS-422 spec of  $4k\Omega$ , and meets the RS-485 "Unit Load" requirement of  $12k\Omega$  minimum.

Receiver inputs function with common mode voltages as great as +9V/-7V outside the power supplies (i.e., +12V and -7V), making them ideal for long networks where induced voltages are a realistic concern.

All the receivers include a "fail-safe if open" function that guarantees a high level receiver output if the receiver inputs are unconnected (floating).

The receiver easily meets the data rate supported by the driver, and the receiver output is tri-statable via the active low  $\overline{\text{RE}}$  input.

7 ------

#### **Driver Features**

The RS-485, RS-422 driver is a differential output device that delivers at least 1.5V across a  $54\Omega$  load (RS-485), and at least 2V across a  $100\Omega$  load (RS-422) even with V<sub>CC</sub> = 3V. The driver features low propagation delay skew to maximize bit width, and to minimize EMI, and it is tri-statable via the active high DE input.

Outputs of the ISL43485 driver are not slew rate limited, so faster output transition times allow data rates of at least 30Mbps.

#### Data Rate, Cables, and Terminations

Twisted pair is the cable of choice for RS-485, RS-422 networks. Twisted pair cables tend to pick up noise and other electromagnetically induced voltages as common mode signals, which are effectively rejected by the differential receivers in this IC.

RS-485, RS-422 are intended for network lengths up to 4000', but the maximum system data rate decreases as the transmission length increases. Devices operating at 30Mbps are often limited to lengths of less than one hundred feet. Figure 6 details the ISL43485's 30Mbps performance driving 200' of "CAT5" cable terminated in  $120\Omega$  at both ends. Note that the differential signal delivered to the receiver at the end of the cable (A-B) still exceeds 1.5V peak. Longer cable lengths are possible by reducing the data rate, as shown in Figure 7 for a data rate of 20Mbps.

To minimize reflections, proper termination is imperative when using this 30Mbps device. In point-to-point, or point-to-multipoint (single driver on bus) networks, the main cable should be terminated in its characteristic impedance (typically  $120\Omega)$  at the end farthest from the driver. In multi-receiver applications, stubs connecting receivers to the main cable should be kept as short as possible. Multipoint (multi-driver) systems require that the main cable be terminated in its characteristic impedance at both ends. Stubs connecting a transceiver to the main cable should be kept as short as possible.

#### **Built-In Driver Overload Protection**

As stated previously, the RS-485 spec requires that drivers survive worst case bus contentions undamaged. The ISL43485 meets this requirement via driver output short circuit current limits, and on-chip thermal shutdown circuitry.

The driver output stages incorporate short circuit current limiting circuitry which ensures that the output current never exceeds the RS-485 spec, even at the common mode voltage range extremes. Additionally, it utilizes a foldback circuit which reduces the short circuit current, and thus the power dissipation, whenever the contending voltage exceeds either supply.

In the event of a major short circuit condition, this device also includes a thermal shutdown feature that disables the drivers whenever the die temperature becomes excessive. This eliminates the power dissipation, allowing the die to cool. The drivers automatically reenable after the die temperature drops about 15 degrees. If the contention persists, the thermal shutdown/reenable cycle repeats until the fault is cleared. Receivers stay operational during thermal shutdown.

#### Low Power Shutdown Mode

This BiCMOS transceiver uses a fraction of the power required by its bipolar counterparts, nevertheless, the ISL43485 includes a shutdown feature that reduces the already low quiescent  $I_{CC}$  to a 15nA trickle. They enter shutdown whenever the receiver and driver are  $\it simultaneously$  disabled ( $\rm \overline{RE}$  =  $\rm V_{CC}$  and DE = GND) for a period of at least 300ns. Disabling both the driver and the receiver for less than 80ns guarantees that shutdown is not entered.

Note that receiver and driver enable times increase when these devices enable from shutdown. Refer to Notes 5-9, at the end of the Electrical Specification table, for more information.

---

# **Typical Performance Curves** $V_{CC} = 3.3V$ , $T_A = 25^{\circ}C$ ; Unless Otherwise Specified

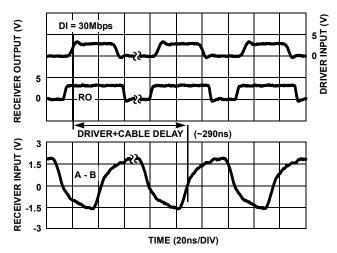


FIGURE 6. DRIVER AND RECEIVER WAVEFORMS DRIVING 200 FEET OF CAT5 CABLE (DOUBLE TERMINATED WITH 120 $\Omega$ )

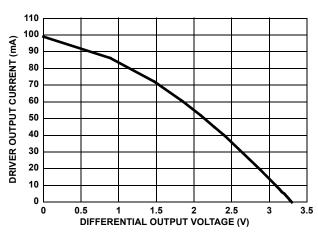


FIGURE 8. DRIVER OUTPUT CURRENT VS DIFFERENTIAL OUTPUT VOLTAGE

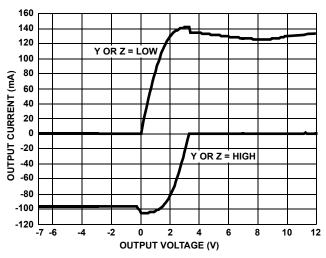


FIGURE 10. DRIVER OUTPUT CURRENT VS SHORT CIRCUIT VOLTAGE

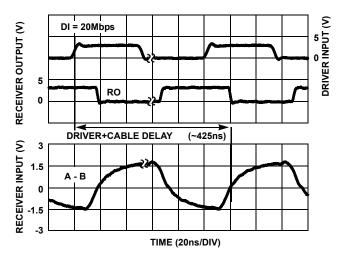


FIGURE 7. DRIVER AND RECEIVER WAVEFORMS DRIVING 300 FEET OF CAT5 CABLE (DOUBLE TERMINATED WITH 120 $\Omega$ )

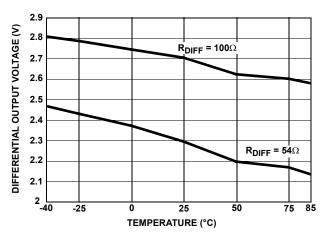


FIGURE 9. DRIVER DIFFERENTIAL OUTPUT VOLTAGE vs TEMPERATURE

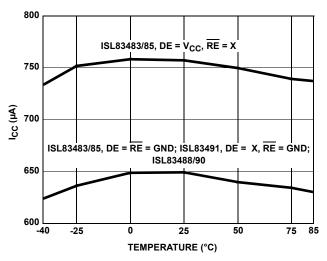


FIGURE 11. SUPPLY CURRENT vs TEMPERATURE

-----

## Typical Performance Curves V<sub>CC</sub> = 3.3V, T<sub>A</sub> = 25°C; Unless Otherwise Specified (Continued)

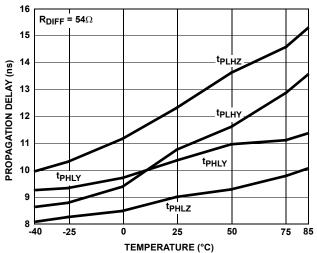


FIGURE 12. DRIVER PROPAGATION DELAY vs TEMPERATURE

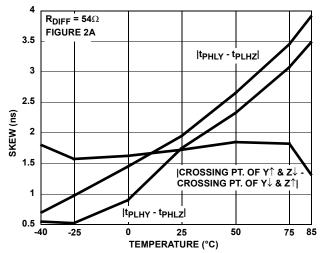


FIGURE 13. DRIVER SKEW vs TEMPERATURE

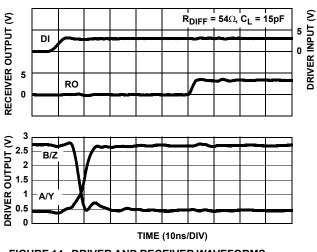


FIGURE 14. DRIVER AND RECEIVER WAVEFORMS, LOW TO HIGH

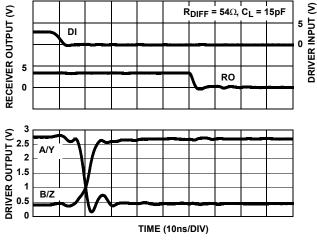


FIGURE 15. DRIVER AND RECEIVER WAVEFORMS, HIGH TO LOW

## Die Characteristics

SUBSTRATE POTENTIAL (POWERED UP):

**GND** 

TRANSISTOR COUNT:

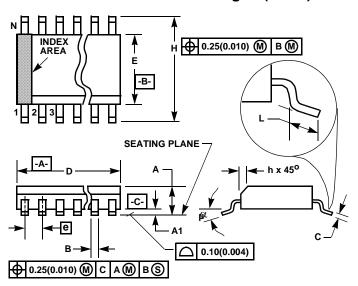
528

PROCESS:

Si Gate BiCMOS

---

## Small Outline Plastic Packages (SOIC)



#### NOTES:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs.
   Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
- Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

#### M8.15 (JEDEC MS-012-AA ISSUE C) 8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

	INCI	HES	MILLIN	IETERS	
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
В	0.013	0.020	0.33	0.51	9
С	0.0075	0.0098	0.19	0.25	-
D	0.1890	0.1968	4.80	5.00	3
Е	0.1497	0.1574	3.80	4.00	4
е	0.050	0.050 BSC		BSC	-
Н	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	8	3	8		7
α	0°	8 <sup>0</sup>	0°	8 <sup>0</sup>	-

Rev. 0 12/93

All Intersil U.S. products are manufactured, assembled and tested utilizing ISO9000 quality systems. Intersil Corporation's quality certifications can be viewed at www.intersil.com/design/quality

Intersil products are sold by description only. Intersil Corporation reserves the right to make changes in circuit design, software and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that data sheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see www.intersil.com